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(71) Applicant (for all designated States except US): **PRESS-
CO TECHNOLOGY, INC.** [US/US]; 29200 Aurora
Road, Solon, OH 44139 (US).

(72) Inventors; and

(75) Inventors/Applicants (for US only): **COCHRAN, Don,
W.** [US/US]; 1745 Epping Court, Gates Mills, OH 44040
(US). **JOHNSON, Benjamin, D.** [US/US]; 5742 Alberta
Drive, Lyndhurst, OH 44010 (US). **KATZ, Jonathan, M.**
[US/US]; 38730 Glenlivet Court, Solon, OH 44139 (US).
MOORE, Mark, W. [US/US]; 847 Stone Hill Oval, Au-
rora, OH 44202 (US). **MORGAN, Noel, E.** [US/US];
6072 Sandpiper Lane, North Olmsted, OH 44070 (US).
ROSS, Denwood, F. [US/US]; 8420 Center Road South,
Austinburg, OH 44010 (US).

(74) Agent: **DREHER, Joseph, D.**; Fay Sharpe LLP, The
Halle Building, 5th Floor, 1228 Euclid Avenue, Cleve-
land, OH 44115-1843 (US).

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(54) Title: DIGITAL HEAT INJECTION BY WAY OF SURFACE EMITTING SEMI-CONDUCTOR DEVICES

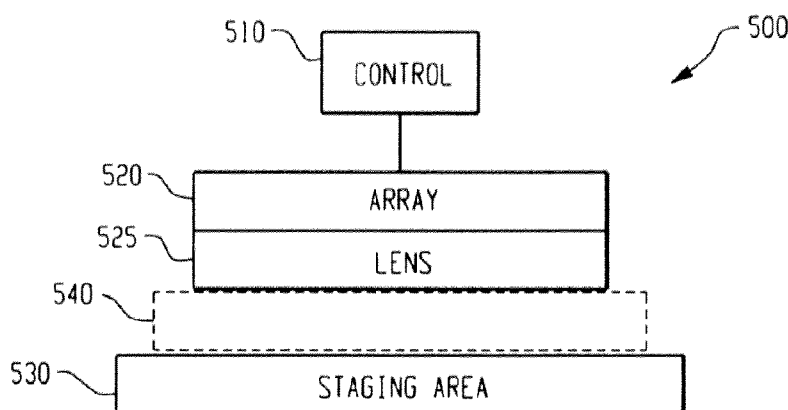


Fig. 3(a)

(57) Abstract: A method and system are provided for digitally injecting heat into a wide range of products by way of incorporation of a special class of semi-conductor lasers, e.g. surface emitting devices. This technique relates to a more specific, economical, and advantageous way of practicing the art of directly injecting narrowband radiant energy that desirously matches the absorption specification of a particular material at a specified wavelength.

